

1. Record Nr.	UNINA9910350301703321
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Titolo	Modeling and Application of Flexible Electronics Packaging // by YongAn Huang, Zhouping Yin, Xiaodong Wan
Pubbl/distr/stampa	Singapore : , : Springer Singapore : , : Imprint : Springer, , 2019
ISBN	981-13-3627-X
Edizione	[1st ed. 2019.]
Descrizione fisica	1 online resource (XVII, 287 p.)
Disciplina	621.381
Soggetti	Electronics Microelectronics Optical materials Electronics - Materials Manufactures Mechanics Mechanics, Applied Computer simulation Electronics and Microelectronics, Instrumentation Optical and Electronic Materials Manufacturing, Machines, Tools, Processes Theoretical and Applied Mechanics Simulation and Modeling
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Nota di contenuto	Advanced Electronics Packaging -- Interfacial Modeling of Flexible Multilayer Structures -- Measurement of Strength of Ultra-Thin Silicon Chip and Interfacial Fracture Energy -- Shear-Assisted Peeling -- Single-Needle Peeling -- Multi-Needle Peeling -- Conformal Peeling -- Laser Lift-Off -- Vacuum-Based Picking-up and Placing-on.
Sommario/riassunto	This book systematically discusses the modeling and application of transfer manipulation for flexible electronics packaging, presenting multiple processes according to the geometric sizes of the chips and devices as well as the detailed modeling and computation steps for each process. It also illustrates the experimental design of the

equipment to help readers easily learn how to use it. This book is a valuable resource for scholars and graduate students in the research field of microelectronics.
